



Advance Product Change Notification

201601001A

Issue Date: 22-Feb-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu and release of 2nd source mold compounds in SOT223

Details of this Planned Change

Scheduled changes affect product types in SOT223 package only.

- (1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
- (2) New mold compound suppliers will be introduced for copper wire products.
- (3) Some product types will be changed to a new leadframe design. Please see the Self Qualification Report for details.

Old product: wire material is Au (with currently used mold compound suppliers and leadframe design)
Changed product: wire material is Cu (with currently used and new mold compound suppliers, partly changed leadframe design) or Au (with currently used and new mold compound suppliers, partly changed leadframe design)

The design and materials of all other components will remain unchanged, i.e. no change of die and die attach. Reliability qualification and full electrical characterization over temperature will be performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Plan this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy and second source material availability, new second source mold

compounds will be added to the BOM. The second sources are already well-established mold compound suppliers for NXP GA discrete semiconductor products.

(3) Standardisation of leadframe design with similar package SOT89. Leadframes with grooves are in production for SOT89 types since 2006.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Samples can be ordered now and will be shipped latest with FPCN issue date.

Impact

No impact to the products' functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 22-Apr-2016.

The Final PCN is planned to be issued on: 22-Apr-2016.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 23-Mar-2016.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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